

## LAMPIRAN

International  
**IR** Rectifier

Data Sheet No. PD66028-M

**IR2111(S) & (PbF)**

### HALF-BRIDGE DRIVER

#### Features

- Floating channel designed for bootstrap operation  
Fully operational to +600V  
Tolerant to negative transient voltage  
dv/dt immune
- Gate drive supply range from 10 to 20V
- Undervoltage lockout for both channels
- CMOS Schmitt-triggered inputs with pull-down
- Matched propagation delay for both channels
- Internally set deadtime
- High side output in phase with input
- Also available LEAD-FREE

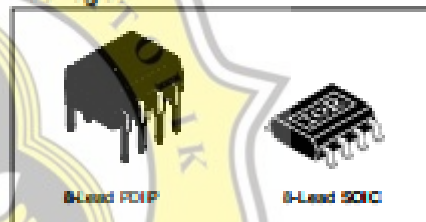
#### Description

The IR2111(S) is a high voltage, high speed power MOSFET and IGBT driver with dependant high and low side reference output channels designed for half-bridge applications. Proprietary HVIC and latch immune CMOS technologies enable ruggedized monolithic construction. Logic input is compatible with standard CMOS outputs. The output drivers feature a high pulse current buffer stage designed to minimize driver cross-conduction. Internal deadtime is provided to avoid shoot-through in the output half-bridge. The floating channel can be used to drive an N-channel power MOSFET or IGBT in the high side configuration which operates up to 600 volts.

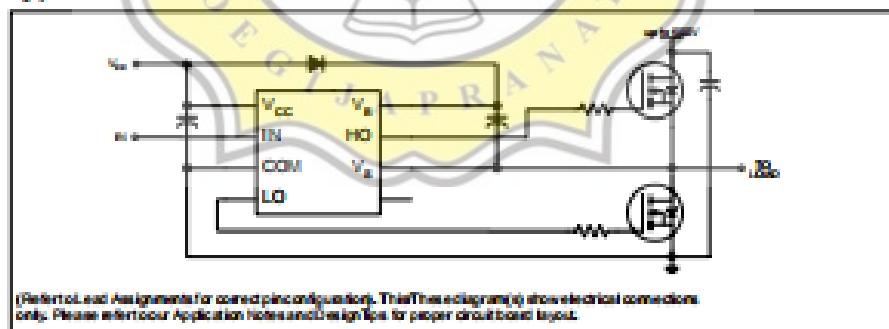
#### Product Summary

$V_{OFFSET}$	600V max.
$I_{O+/-}$	200 mA / 420 mA
$V_{OUT}$	10 - 20V
$t_{ON/OFF}$ (typ.)	750 & 150 ns
Deadtime (typ.)	650 ns

#### Packages



#### Typical Connection



www.irf.com

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# TLP250

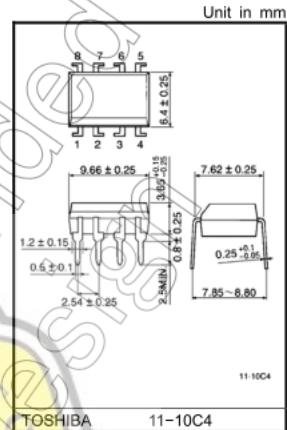
Transistor Inverter  
 Inverter For Air Conditioner  
 IGBT Gate Drive  
 Power MOS FET Gate Drive

The TOSHIBA TLP250 consists of a GaAlAs light emitting diode and a integrated photodetector.  
 This unit is 8-lead DIP package.  
 TLP250 is suitable for gate driving circuit of IGBT or power MOS FET.

- Input threshold current:  $I_F=5\text{mA}(\text{max.})$
- Supply current ( $I_{CC}$ ):  $11\text{mA}(\text{max.})$
- Supply voltage ( $V_{CC}$ ):  $10\text{--}35\text{V}$
- Output current ( $I_O$ ):  $\pm 1.5\text{A}(\text{max.})$
- Switching time ( $t_{pLH}/t_{pHL}$ ):  $0.5\mu\text{s}(\text{max.})$
- Isolation voltage:  $2500\text{V}_{\text{rms}}(\text{min.})$
- UL recognized: UL1577, file No.E67349
- Option(D4)

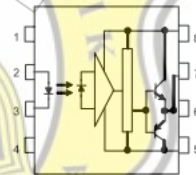
VDE Approved : DIN EN60747-5-2  
 Maximum Operating Insulation Voltage :  $890\text{V}_{\text{PK}}$   
 Highest Permissible Over Voltage :  $4000\text{V}_{\text{PK}}$

(Note):When a EN60747-5-2 approved type is needed,  
 Please designate "Option(D4)"



Weight: 0.54 g (typ.)

**Pin Configuration (top view)**

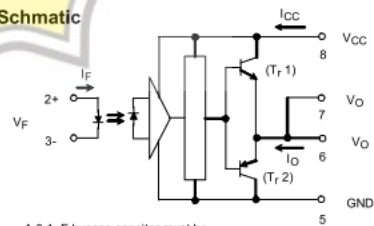


- 1 : N.C.
- 2 : Anode
- 3 : Cathode
- 4 : N.C.
- 5 : GND
- 6 :  $V_O$  (Output)
- 7 :  $V_O$
- 8 :  $V_{CC}$

**Truth Table**

		$T_{r1}$	$T_{r2}$
Input LED	On	On	Off
	Off	Off	On

**Schematic**



Technische Information / Technical Information

IGBT-Module  
IGBT-modules

FF300R12KS4



62mm C-Serien Modul mit schnellem IGBT2 für hochfrequentes Schalten  
62mm C-series module with the fast IGBT2 for high-frequency switching

IGBT, Wechselrichter / IGBT, Inverter


Höchstzulässige Werte / Maximum Rated Values

Kollektor-Emitter-Spannung Collector-emitter voltage	$T_J = 25^\circ\text{C}$	$V_{CE}$	1200	V
Kollektor-Dauerstrom Continuous DC collector current	$T_C = 60^\circ\text{C}, T_{q, \text{max}} = 150^\circ\text{C}$ $T_C = 25^\circ\text{C}, T_{q, \text{max}} = 150^\circ\text{C}$	$I_{C, \text{max}}$ $I_C$	300 370	A A
Periodischer Kollektor-Spitzenstrom Repetitive peak collector current	$I_p = 1 \text{ ma}$	$I_{C, \text{max}}$	600	A
Gesamt-Verlustleistung Total power dissipation	$T_C = 25^\circ\text{C}, T_{q, \text{max}} = 150$	$P_{\text{tot}}$	1950	W
Gate-Emitter-Spitzenspannung Gate-emitter peak voltage		$V_{GE}$	+/-20	V

Charakteristische Werte / Characteristic Values

			min.	typ.	max.		
Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage	$I_C = 300 \text{ A}, V_{CE} = 15 \text{ V}$ $I_C = 300 \text{ A}, V_{CE} = 15 \text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	$V_{CE, \text{sat}}$	3,20 3,85	3,75	V V	
Gate-Schwelleffspannung Gate threshold voltage	$I_C = 12,0 \text{ mA}, V_{GE} = V_{GE}, T_J = 25^\circ\text{C}$		$V_{GE, \text{th}}$	4,5	5,5	6,5	V
Gateladung Gate charge	$V_{GE} = -15 \text{ V} \dots +15 \text{ V}$		$Q_G$	3,20			$\mu\text{C}$
Interner Gatewiderstand Internal gate resistor	$T_J = 25^\circ\text{C}$		$R_{\text{int}}$	1,0			$\Omega$
Eingangskapazität Input capacitance	$f = 1 \text{ MHz}, T_J = 25^\circ\text{C}, V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}$		$C_{\text{in}}$	20,0			nF
Rückwirkungskapazität Reverse transfer capacitance	$f = 1 \text{ MHz}, T_J = 25^\circ\text{C}, V_{CE} = 25 \text{ V}, V_{GE} = 0 \text{ V}$		$C_{\text{tr}}$	1,40			nF
Kollektor-Emitter-Reststrom Collector-emitter cut-off current	$V_{CE} = 1200 \text{ V}, V_{GE} = 0 \text{ V}, T_J = 25^\circ\text{C}$		$I_{C, \text{off}}$			5,0	mA
Gate-Emitter-Reststrom Gate-emitter leakage current	$V_{CE} = 0 \text{ V}, V_{GE} = 20 \text{ V}, T_J = 25^\circ\text{C}$		$I_{GE, \text{off}}$			-400	nA
Einachalverzögerungszeit, induktive Last Turn-on delay time, inductive load	$I_C = 300 \text{ A}, V_{CE} = 600 \text{ V}$ $V_{GE} = \pm 15 \text{ V}$ $R_{\text{load}} = 3,0 \Omega$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	$t_{\text{on}}$	6,10 9,11			$\mu\text{s}$ $\mu\text{s}$
Anstiegszeit, induktive Last Rise time, inductive load	$I_C = 300 \text{ A}, V_{CE} = 600 \text{ V}$ $V_{GE} = \pm 15 \text{ V}$ $R_{\text{load}} = 3,0 \Omega$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	$t_r$	0,06 0,07			$\mu\text{s}$ $\mu\text{s}$
Abchaltverzögerungszeit, induktive Last Turn-off delay time, inductive load	$I_C = 300 \text{ A}, V_{CE} = 600 \text{ V}$ $V_{GE} = \pm 15 \text{ V}$ $R_{\text{load}} = 3,0 \Omega$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	$t_{\text{off}}$	0,53 0,55			$\mu\text{s}$ $\mu\text{s}$
Fallzeit, induktive Last Fall time, inductive load	$I_C = 300 \text{ A}, V_{CE} = 600 \text{ V}$ $V_{GE} = \pm 15 \text{ V}$ $R_{\text{load}} = 3,0 \Omega$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	$t_f$	0,03 0,04			$\mu\text{s}$ $\mu\text{s}$
Einachalverlustenergie pro Puls Turn-on energy loss per pulse	$I_C = 300 \text{ A}, V_{CE} = 600 \text{ V}, L_s = 60 \text{ nH}$ $V_{GE} = \pm 15 \text{ V}, dI/dt = 5000 \text{ A}/\mu\text{s}$ $R_{\text{load}} = 3,0 \Omega$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	$E_{\text{on}}$	25,0			mJ mJ
Abchaltverlustenergie pro Puls Turn-off energy loss per pulse	$I_C = 300 \text{ A}, V_{CE} = 600 \text{ V}, L_s = 60 \text{ nH}$ $V_{GE} = \pm 15 \text{ V}, dI/dt = 7500 \text{ A}/\mu\text{s}$ $R_{\text{load}} = 3,0 \Omega$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	$E_{\text{off}}$	15,0			mJ mJ
Kurzschlussverhalten SC data	$V_{CE} \leq 15 \text{ V}, V_{GE} = 900 \text{ V}$ $V_{\text{th}} = V_{\text{th}} - L_{\text{sc}} \cdot dI/dt$ $I_{\text{sc}} \leq 10 \text{ A}, T_J = 125^\circ\text{C}$		$I_{\text{sc}}$	2000			A
Wärmeleitfähigkeit, Chip bis Gehäuse Thermal resistance, junction to case	pro IGBT / per IGBT		$R_{\text{th(j-c)}}$			0,064	K/W
Wärmeleitfähigkeit, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink	pro IGBT / per IGBT $\lambda_{\text{case}} = 1 \text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{\text{package}} = 1 \text{ W}/(\text{m}\cdot\text{K})$		$R_{\text{th(c-h)}}$			0,05	K/W
Temperatur im Schaltbetrieb Temperature under switching conditions			$T_{q, \text{sw}}$	-40		125	$^\circ\text{C}$

prepared by: MK      date of publication: 2013-10-03  
approved by: WR      revision: 3.2



# MICROCHIP PIC18F2455/2550/4455/4550

## 28/40/44-Pin High-Performance, Enhanced Flash USB Microcontrollers with nanoWatt Technology

### Universal Serial Bus Features:

- USB V2.0 Compliant SIE
- Low-speed (1.5 Mb/s) and full-speed (12 Mb/s)
- Supports control, interrupt, isochronous and bulk transfers
- Supports up to 32 endpoints (16 bidirectional)
- 1-Kbyte dual access RAM for USB
- On-board USB transceiver with on-chip voltage regulator
- Interface for off-chip USB transceiver
- Streaming Parallel Port (SPP) for USB streaming transfers (40/44-pin devices only)

### Power Managed Modes:

- Run: CPU on, peripherals on
- Idle: CPU off, peripherals on
- Sleep: CPU off, peripherals off
- Idle mode currents down to 5.8  $\mu$ A typical
- Sleep current down to 0.1  $\mu$ A typical
- Timer1 oscillator: 1.1  $\mu$ A typical, 32 KHz, 2V
- Watchdog Timer: 2.1  $\mu$ A typical
- Two-Speed Oscillator Start-up

### Flexible Oscillator Structure:

- Five Crystal modes, including High-Precision PLL for USB
- Two External RC modes, up to 4 MHz
- Two External Clock modes, up to 40 MHz
- Internal oscillator block:
  - 8 user selectable frequencies, from 31 kHz to 8 MHz
  - User tunable to compensate for frequency drift
- Secondary oscillator using Timer1 @ 32 kHz
- Fail-Safe Clock Monitor
  - Allows for safe shutdown if any clock stops

### Peripheral Highlights:

- High current sink/source: 25 mA/25 mA
- Three external interrupts
- Four Timer modules (Timer0 to Timer3)
- Up to 2 Capture/Compare/PWM (CCP) modules:
  - Capture is 16-bit, max. resolution 6.25 ns (Tcy/16)
  - Compare is 16-bit, max. resolution 100 ns (Tcy)
  - PWM output: PWM resolution is 1 to 10-bit
- Enhanced Capture/Compare/PWM (ECCP) module:
  - Multiple output modes
  - Selectable polarity
  - Programmable dead-time
  - Auto-Shutdown and Auto-Restart
- Addressable USART module:
  - LIN bus support
- Master Synchronous Serial Port (MSSP) module supporting 3-wire SPI™ (all 4 modes) and I<sup>2</sup>C™ Master and Slave modes
- 10-bit, up to 13-channels Analog-to-Digital Converter module (ADC) with programmable acquisition time
- Dual analog comparators with input multiplexing

### Special Microcontroller Features:

- C compiler optimized architecture with optional extended instruction set
- 100,000 erase/write cycle Enhanced Flash program memory typical
- 1,000,000 erase/write cycle data EEPROM memory typical
- Flash/data EEPROM retention: > 40 years
- Self-programmable under software control
- Priority levels for interrupts
- 8 x 8 Single Cycle Hardware Multiplier
- Extended Watchdog Timer (WDT):
  - Programmable period from 41 ms to 131s
- Programmable Code Protection
- Single-supply 5V In-Circuit Serial Programming™ (ICSP™) via two pins
- In-Circuit Debug (ICD) via two pins
- Wide operating voltage range (2.0V to 5.5V)

Device	Program Memory		Data Memory		IO	10-Bit A/D (ch)	CCP/ ECCP (PWM)	SPP	MSSP		USART	Comparators	Timers 8/16-bit
	FLASH (bytes)	# Single-Word Instructions	SRAM (bytes)	EEPROM (bytes)					SPI	Master I <sup>2</sup> C			
PIC18F2455	24K	12288	2048	256	24	10	2/0	No	Y	Y	1	2	1/3
PIC18F2550	32K	16384	2048	256	24	10	2/0	No	Y	Y	1	2	1/3
PIC18F4455	24K	12288	2048	256	35	13	1/1	Yes	Y	Y	1	2	1/3
PIC18F4550	32K	16384	2048	256	35	13	1/1	Yes	Y	Y	1	2	1/3

DC/DC Converter  
B\_S-1WR2 & B\_D-1WR2 series

MORNSUN®

1W, Fixed input voltage, Isolated & unregulated single output



UL US CE Patent Protection RoHS

FEATURES

- Continuous short-circuit protection
- Operating temperature range: -40°C to +105°C
- Conversion efficiency high up to 80%
- Miniature SIP/DIP package, International standard pin-out
- Isolation voltage: 1.5K VDC
- EN60950, UL60950 Approval

B\_S-1WR2 & B\_D-1WR2 series are specially designed for applications where an isolated voltage is required in a distributed power supply system. They are suitable for

1. Where the voltage of the input power supply is stable (voltage variation <math>\pm 0.5\%</math>);
2. Where isolation between input and output is necessary (isolation voltage <math>\ge 1500\text{VDC}</math>);
3. Where the output voltage regulation and the ripple & noise of the output voltage is not strictly required;
4. Typical application: digital circuit condition; normal low-frequency artificial circuit condition; relay drive circuit and data switching circuit condition, etc.

Selection Guide							
Certification	Part No.	Input Voltage (VDC)		Output		Efficiency (%) (Min./Typ.) @ Full Load	Max. Capacitive Load(μF)
		Nominal (Range)	Output Voltage (VDC)	Output Current (mA)(Max./Min.)			
UL/CE	B0005-1WR2	3.3 (2.57-3.63)	3.3	300/30	68/72	200	
	B0005-1WR2		5	200/20	75/80		
	B00125-1WR2		12	84/9	75/80		
	B0030-1WR2		3.3	300/30	68/72		
	B0030-1WR2		5	200/20	75/80		
	B0030-1WR2		3.3	300/30	68/72		
UL/CE	B0095-1WR2	5 (4.5-5.5)	5	200/20	75/80		
	B0095-1WR2		9	111/12	75/80		
	B0125-1WR2		12	84/9	75/80		
	B015-1WR2		15	67/7	75/80		
	B024-1WR2		24	40/4	75/80		
	B030-1WR2		3.3	300/30	68/72		
UL/CE	B030-1WR2	12 (10.8-13.2)	5	200/20	75/80		
	B030-1WR2		9	111/12	75/80		
	B030-1WR2		12	84/9	75/80		
	B030-1WR2		15	67/7	75/80		
	B030-1WR2		24	40/4	75/80		
	B030-1WR2		3.3	300/30	68/72		
UL/CE	B12030-1WR2	12 (10.8-13.2)	5	200/20	75/80		
	B12030-1WR2		9	111/12	75/80		
	B12030-1WR2		12	84/9	75/80		
	B12030-1WR2		15	67/7	75/80		
	B12030-1WR2		3.3	300/30	68/72		
	B12030-1WR2		5	200/20	75/80		

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**2.52%** PLAGIARISM  
APPROXIMATELY

## Report #11635934

BAB IPENDAHULUAN Latar Belakang Di zaman modern, penggunaan sumber daya terbarukan seperti matahari, udara, angin, dan sumber daya lainnya semakin meningkat. [1] Dalam kehidupan sehari-hari, energi listrik sangat dibutuhkan, oleh karena itu energi matahari digunakan sebagai sumber energi listrik yang ramah lingkungan dan terbarukan. Perangkat yang disebut panel surya atau fotovoltaik atau PV dan konverter diperlukan untuk memanfaatkan energi surya ini, konverter ini sebagian besar digunakan dalam teknologi terbaru untuk menghitung beban daya. [2] Output panel surya (PV) dikenal sebagai DC dan output panel surya yang dimaksimalkan oleh MPPT yang dikenal sebagai AC menjadi sumber energi untuk peralatan rumah tangga dan peralatan industri. [3]. Inverter bertingkat umum dibentuk dari tiga topologi dasar sementara topologi lain dikembangkan melalui kombinasi atau modifikasi topologi dasar untuk membentuk inverter bertingkat banyak. Konstruksi inverter konvensional dibatasi oleh kualitas komponen daya mereka [4] Topologi yang paling banyak digunakan adalah flying capacitor, diode-clamp, and cascade constructions. Namun, semakin banyak penyebab tingkat -n meningkatkan volume, biaya, dan jumlah saklar dari inverter. Desain asimetris umumnya memenuhi tujuan ini dan dengan meningkatnya tingkatan, Semakin tinggi tingkat inverter, semakin kecil